

TOSHIBA Field Effect Transistor Silicon N Channel MOS Type ( $\pi$ -MOSV)**2SK3472**

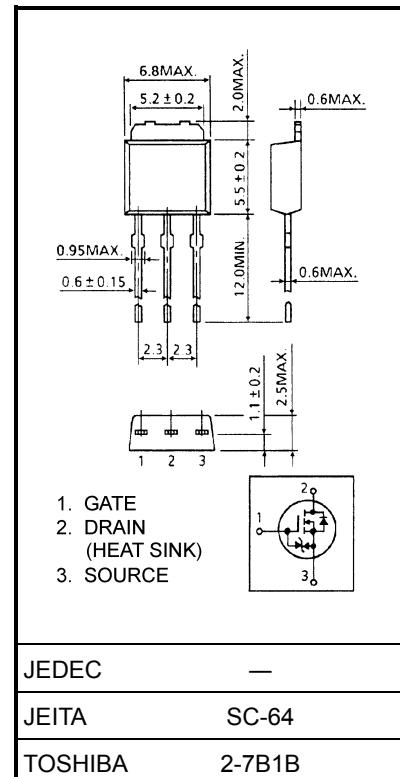
## Switching Regulator Applications

Unit: mm

- Low drain-source ON resistance:  $R_{DS(ON)} = 4.0 \text{ m}\Omega$  (typ.)
- High forward transfer admittance:  $|Y_{fs}| = 0.8 \text{ S}$  (typ.)
- Low leakage current:  $I_{DSS} = 100 \mu\text{A}$  (max) ( $V_{DS} = 450 \text{ V}$ )
- Enhancement-model:  $V_{th} = 2.0$  to  $4.0 \text{ V}$  ( $V_{DS} = 10 \text{ V}$ ,  $I_D = 1 \text{ mA}$ )

**Maximum Ratings ( $T_c = 25^\circ\text{C}$ )**

| Characteristics                                      |                | Symbol    | Rating     | Unit             |
|--|----------------|-----------|------------|------------------|
| Drain-source voltage                                 |                | $V_{DSS}$ | 450        | V                |
| Drain-gate voltage ( $R_{GS} = 20 \text{ k}\Omega$ ) |                | $V_{DGR}$ | 450        | V                |
| Gate-source voltage                                  |                | $V_{GSS}$ | $\pm 30$   | V                |
| Drain current  | DC (Note 1)    | $I_D$     | 1          | A                |
|  | Pulse (Note 1) | $I_{DP}$  | 2          | A                |
| Drain power dissipation                              |                | $P_D$     | 20         | W                |
| Single pulse avalanche energy (Note 2)               |                | $E_{AS}$  | 122        | mJ               |
| Avalanche current                                    |                | $I_{AR}$  | 1          | A                |
| Repetitive avalanche energy (Note 3)                 |                | $E_{AR}$  | 2          | mJ               |
| Channel temperature                                  |                | $T_{ch}$  | 150        | $^\circ\text{C}$ |
| Storage temperature range                            |                | $T_{stg}$ | -55 to 150 | $^\circ\text{C}$ |



Weight: 0.36 g (typ.)

**Thermal Characteristics**

| Characteristics                        | Symbol                | Max  | Unit               |
|--|-----------------------|------|--------------------|
| Thermal resistance, channel to case    | $R_{th}(\text{ch-c})$ | 6.25 | $^\circ\text{C/W}$ |
| Thermal resistance, channel to ambient | $R_{th}(\text{ch-a})$ | 125  | $^\circ\text{C/W}$ |

Note 1: Please use devices on condition that the channel temperature is below  $150^\circ\text{C}$ .Note 2:  $V_{DD} = 90 \text{ V}$ ,  $T_{ch} = 25^\circ\text{C}$  (initial),  $L = 203 \text{ mH}$ ,  $R_G = 25 \Omega$ ,  $I_{AR} = 1 \text{ A}$ 

Note 3: Repetitive rating: pulse width limited by maximum channel temperature

This transistor is an electrostatic sensitive device. Please handle with caution.

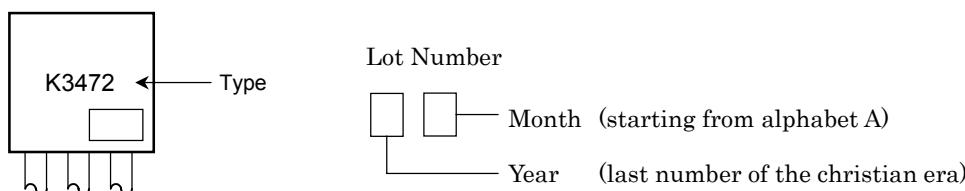
Electrical Characteristics ( $T_c = 25^\circ\text{C}$ )

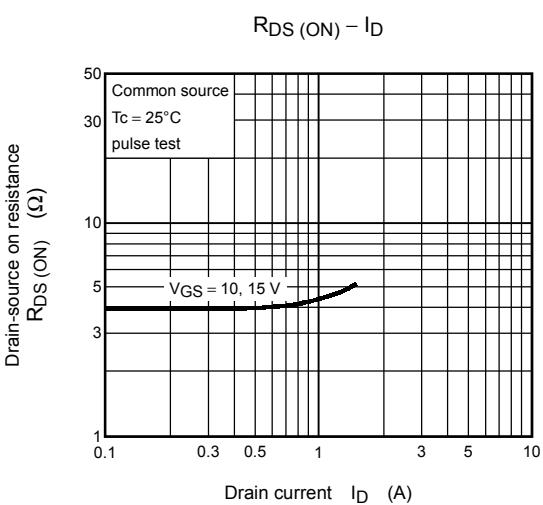
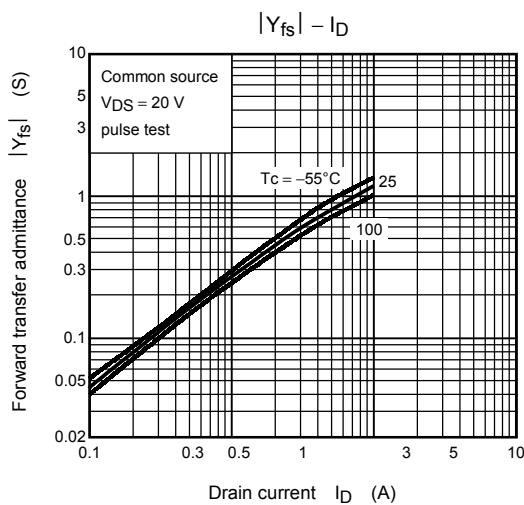
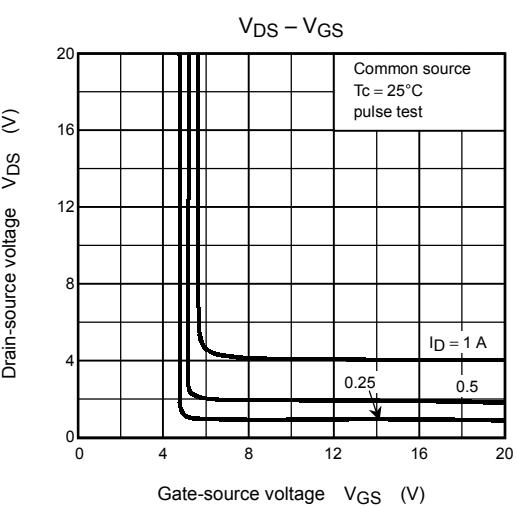
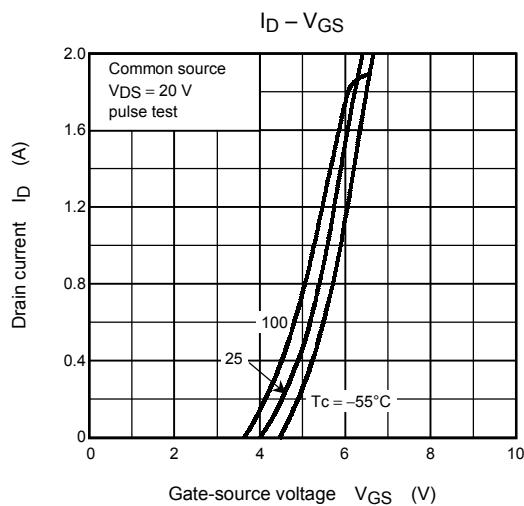
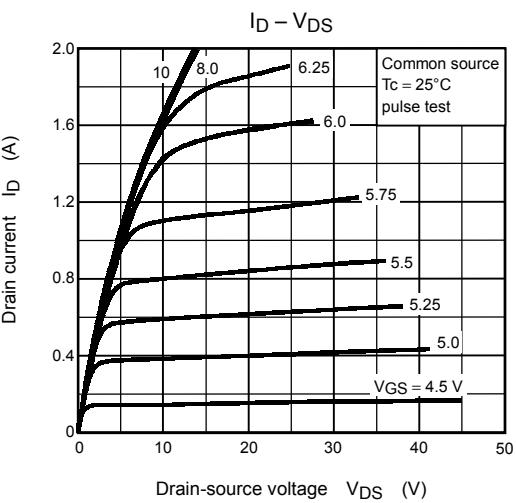
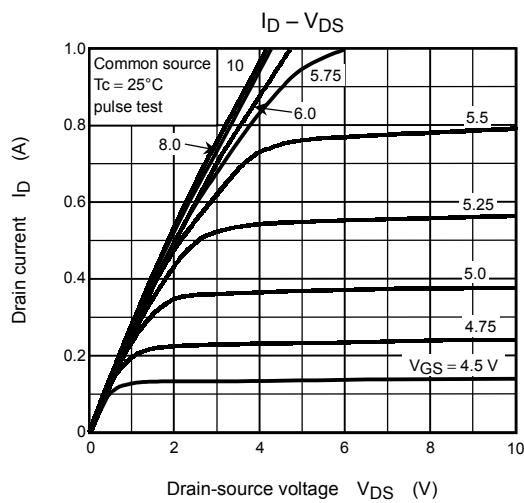
| Characteristics                                 | Symbol                      | Test Condition  | Min  | Typ. | Max      | Unit          |             |
|---|-----------------------------|---|--|------|----------|---------------|-------------|
| Gate leakage current                            | $I_{GSS}$                   | $V_{GS} = \pm 25\text{ V}$ , $V_{DS} = 0\text{ V}$                          | —  | —    | $\pm 10$ | $\mu\text{A}$ |             |
| Drain-source breakdown voltage                  | $V_{(\text{BR})\text{GSS}}$ | $I_G = \pm 10\text{ }\mu\text{A}$ , $V_{DS} = 0\text{ V}$                   | $\pm 30$   | —    | —        | $\text{V}$    |             |
| Drain cut-OFF current                           | $I_{DSS}$                   | $V_{DS} = 450\text{ V}$ , $V_{GS} = 0\text{ V}$                             | —  | —    | 100      | $\mu\text{A}$ |             |
| Drain-source breakdown voltage                  | $V_{(\text{BR})\text{DSS}}$ | $I_D = 10\text{ mA}$ , $V_{GS} = 0\text{ V}$                                | 450  | —    | —        | $\text{V}$    |             |
| Gate threshold voltage                          | $V_{th}$                    | $V_{DS} = 10\text{ V}$ , $I_D = 1\text{ mA}$                                | 2.0  | —    | 4.0      | $\text{V}$    |             |
| Drain-source ON resistance                      | $R_{DS(\text{ON})}$         | $V_{GS} = 10\text{ V}$ , $I_D = 0.5\text{ A}$                               | —  | 4.0  | 4.6      | $\Omega$      |             |
| Forward transfer admittance                     | $ Y_{fs} $                  | $V_{DS} = 10\text{ V}$ , $I_D = 0.5\text{ A}$                               | 0.3  | 0.8  | —        | $\text{S}$    |             |
| Input capacitance                               | $C_{iss}$                   | $V_{DS} = 25\text{ V}$ , $V_{GS} = 0\text{ V}$ , $f = 1\text{ MHz}$         | —  | 180  | —        | $\text{pF}$   |             |
| Reverse transfer capacitance                    | $C_{rss}$                   |   | —  | 2    | —        |               |             |
| Output capacitance                              | $C_{oss}$                   |   | —  | 20   | —        |               |             |
| Switching time                                  | Rise time                   | $t_r$   | <br>$V_{GS}$ 10 V<br>0 V<br>$I_D = 0.5\text{ A}$<br>$V_{OUT}$<br>$R_L = 400\text{ }\Omega$<br>$V_{DD} \approx 200\text{ V}$<br>Duty $\leq 1\%$ , $t_w = 10\text{ }\mu\text{s}$ | —    | 7        | —             | $\text{ns}$ |
|   | Turn-ON time                | $t_{on}$  |  | —    | 15       | —             |             |
|   | Fall time                   | $t_f$   |  | —    | 30       | —             |             |
|   | Turn-OFF time               | $t_{off}$   |  | —    | 70       | —             |             |
| Total gate charge (gate-source plus gate-drain) | $Q_g$                       | $V_{DD} \approx 360\text{ V}$ , $V_{GS} = 10\text{ V}$ , $I_D = 1\text{ A}$ | —  | 5    | —        | $\text{nC}$   |             |
| Gate-source charge                              | $Q_{gs}$                    |   | —  | 3    | —        |               |             |
| Gate-drain ("miller") charge                    | $Q_{gd}$                    |   | —  | 2    | —        |               |             |

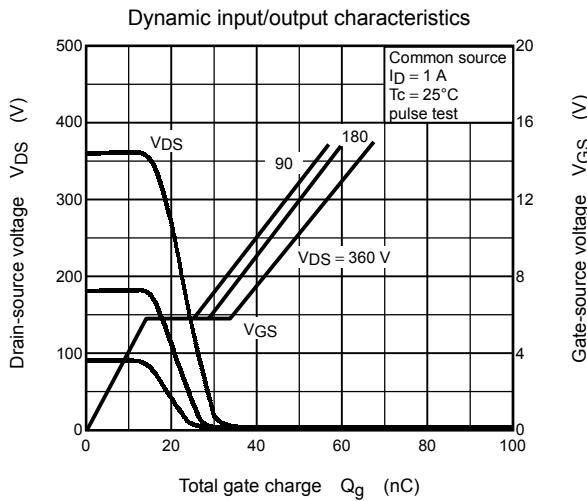
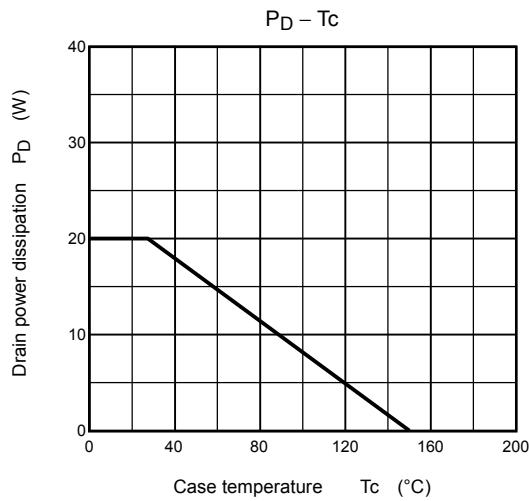
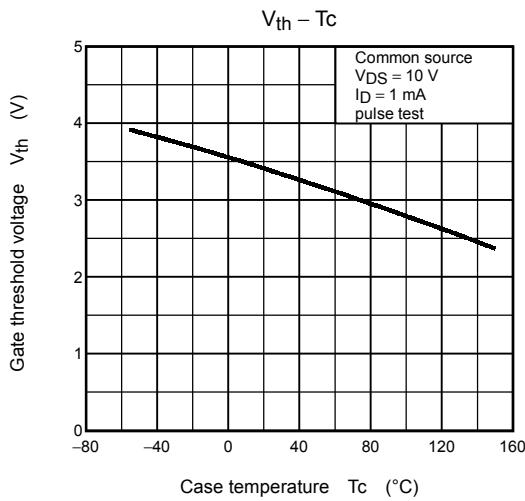
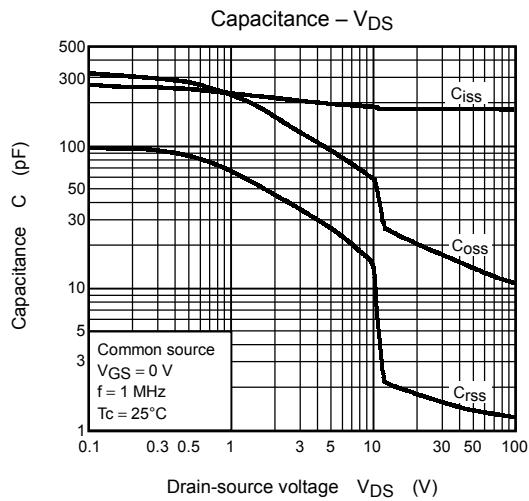
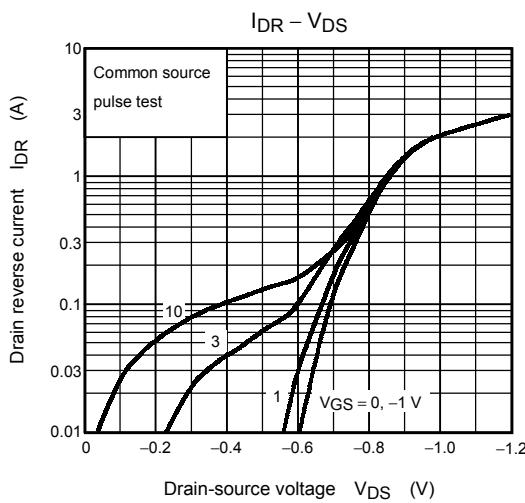
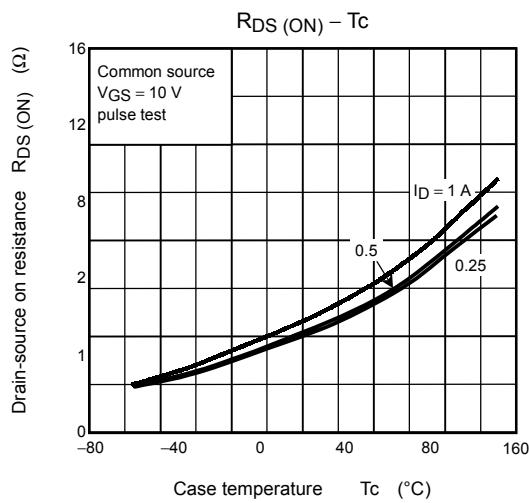
Source-Drain Ratings and Characteristics ( $T_c = 25^\circ\text{C}$ )

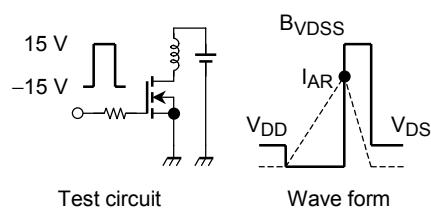
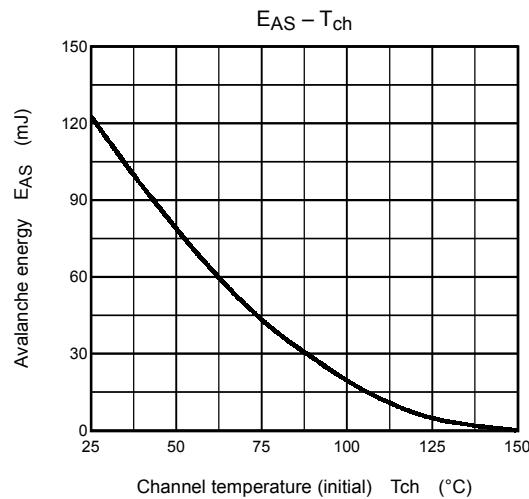
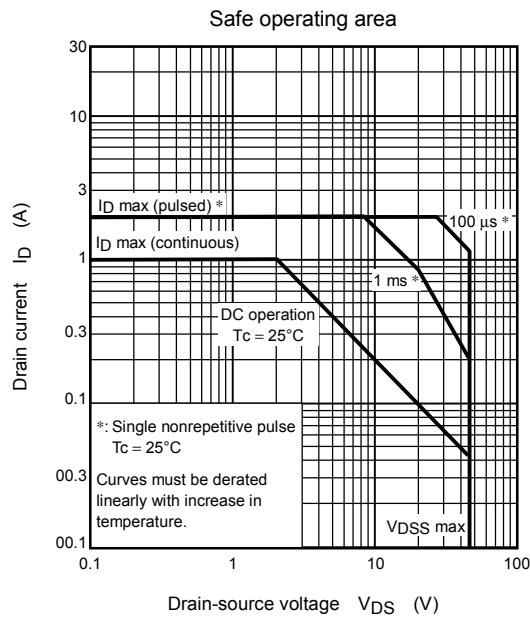
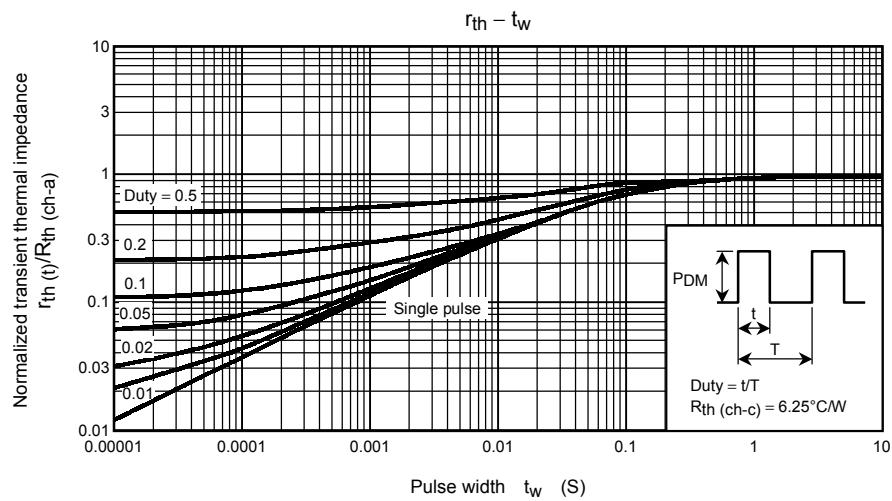
| Characteristics                           | Symbol    | Test Condition   | Min | Typ. | Max  | Unit          |
|---|-----------|--|-----|------|------|---------------|
| Continuous drain reverse current (Note 1) | $I_{DR}$  | —  | —   | —    | 1    | $\text{A}$    |
| Pulse drain reverse current (Note 1)      | $I_{DRP}$ | —  | —   | —    | 2    | $\text{A}$    |
| Forward voltage (diode)                   | $V_{DSF}$ | $I_{DR} = 1\text{ A}$ , $V_{GS} = 0\text{ V}$  | —   | —    | -1.7 | $\text{V}$    |
| Reverse recovery time                     | $t_{rr}$  | $I_{DR} = 1\text{ A}$ , $V_{GS} = 0\text{ V}$ ,<br>$dI_{DR}/dt = 100\text{ A}/\mu\text{s}$ | —   | 350  | —    | $\mu\text{s}$ |
| Reverse recovery charge                   | $Q_{rr}$  | —  | —   | 1.3  | —    | $\mu\text{C}$ |

## Marking









$$R_G = 25 \Omega$$

$$V_{DD} = 90 \text{ V}, L = 203 \text{ mH}$$

$$E_{AS} = \frac{1}{2} \cdot L \cdot I^2 \cdot \left( \frac{B_{VDSS}}{B_{VDSS} - V_{DD}} \right)$$

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